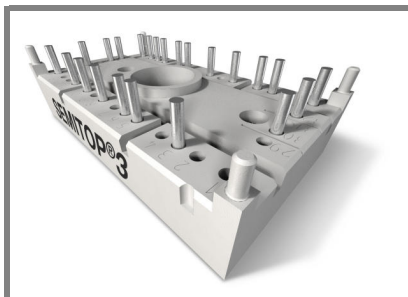


SK60GB123



SEMITOP® 3

IGBT Module

SK60GB123

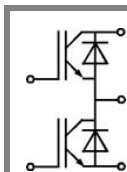
Preliminary Data

Features

- Compact design
- One screw mounting
- Heat transfer and isolation through direct copper bonded aluminium oxide ceramic (DCB)
- High short circuit capability
- Low tail current with low temperature dependence

Typical Applications*

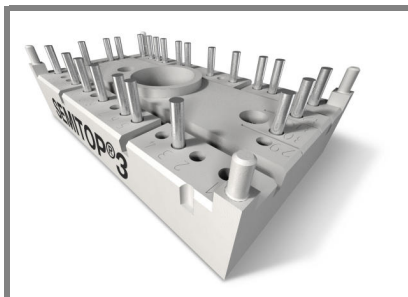
- Switching (not for linear use)
- Inverter
- Switched mode power supplies
- UPS



GB

Absolute Maximum Ratings		T _s = 25 °C, unless otherwise specified	
Symbol	Conditions	Values	Units
IGBT			
V _{CES}	T _j = 25 °C	1200	V
I _C	T _j = 125 °C	T _s = 25 °C	58 A
		T _s = 80 °C	40 A
I _{CRM}	I _{CRM} = 2 × I _{Cnom}	100	A
V _{GES}		± 20	V
t _{psc}	V _{CC} = 600 V; V _{GE} ≤ 20 V; T _j = 125 °C V _{CES} < 1200 V	10	μs
Inverse Diode			
I _F	T _j = 150 °C	T _s = 25 °C	57 A
		T _s = 80 °C	38 A
I _{FRM}	I _{FRM} = 2 × I _{Fnom}		A
I _{FSM}	t _p = 10 ms; half sine wave T _j = 150 °C	550	A
Module			
I _{t(RMS)}			A
T _{vj}		-40 ... +150	°C
T _{stg}		-40 ... +125	°C
V _{isol}	AC, 1 min.	2500	V

Characteristics		T _s = 25 °C, unless otherwise specified			
Symbol	Conditions	min.	typ.	max.	Units
IGBT					
V _{GE(th)}	V _{GE} = V _{CE} , I _C = 2 mA	4,5	5,5	6,5	V
I _{CES}	V _{GE} = 0 V, V _{CE} = V _{CES}	T _j = 25 °C		0,3	mA
		T _j = 125 °C			mA
I _{GES}	V _{CE} = 0 V, V _{GE} = 30 V			300	nA
V _{CE0}		T _j = 25 °C	1,2		V
		T _j = 125 °C	1,2		V
r _{CE}	V _{GE} = 15 V	T _j = 25 °C	26		mΩ
		T _j = 125 °C	38		mΩ
V _{CE(sat)}	I _{Cnom} = 50 A, V _{GE} = 15 V	T _j = 25 °C _{chiplev.}	2,5	3	V
		T _j = 125 °C _{chiplev.}	3,1	3,7	V
C _{ies}	V _{CE} = 25 V, V _{GE} = 0 V	f = 1 MHz	3,3		nF
C _{oes}			0,5		nF
C _{res}			0,22		nF
t _{d(on)}	R _{Gon} = 22 Ω	V _{CC} = 600V I _C = 50A	40		ns
t _r			50		ns
E _{on}			7,6		mJ
t _{d(off)}	R _{Goff} = 22 Ω	T _j = 125 °C V _{GE} = ±15V	380		ns
t _f			75		ns
E _{off}			5,1		mJ
R _{th(j-s)}	per IGBT			0,6	K/W



SEMITOR® 3

IGBT Module

SK60GB123

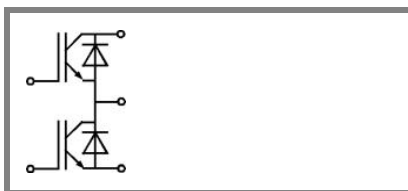
Preliminary Data

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- Switching (not for linear use)
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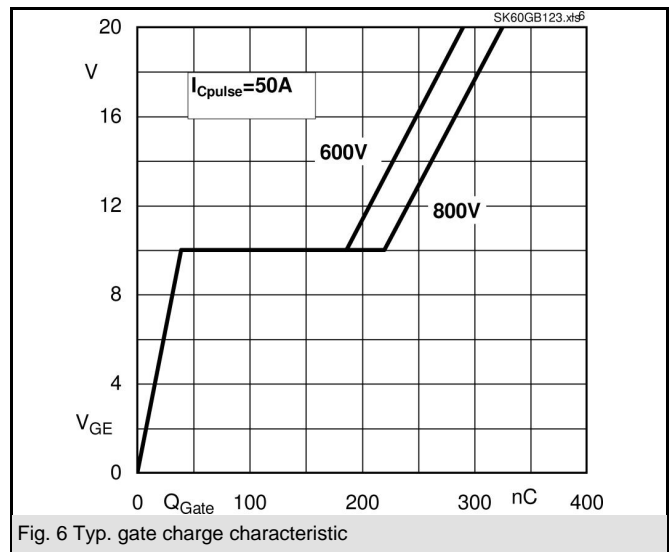
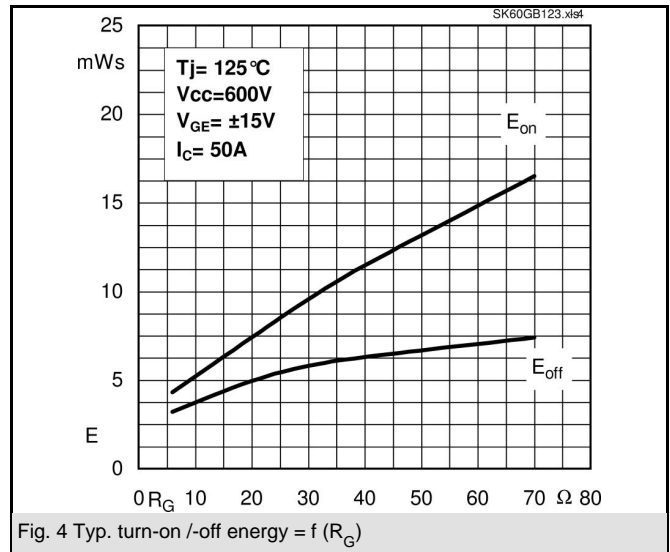
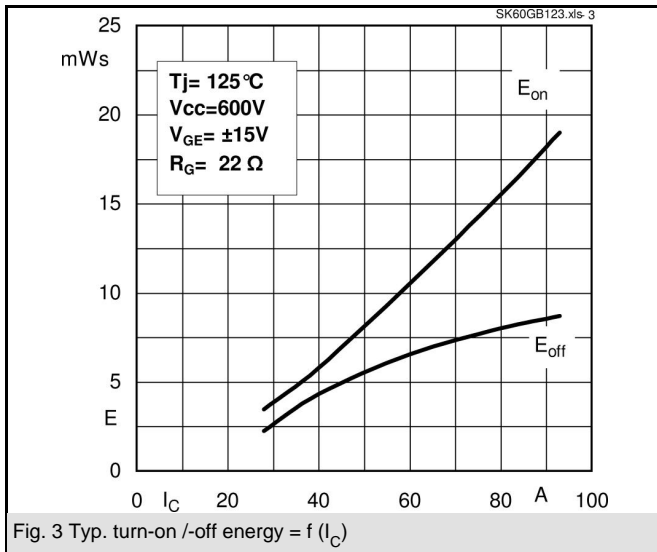
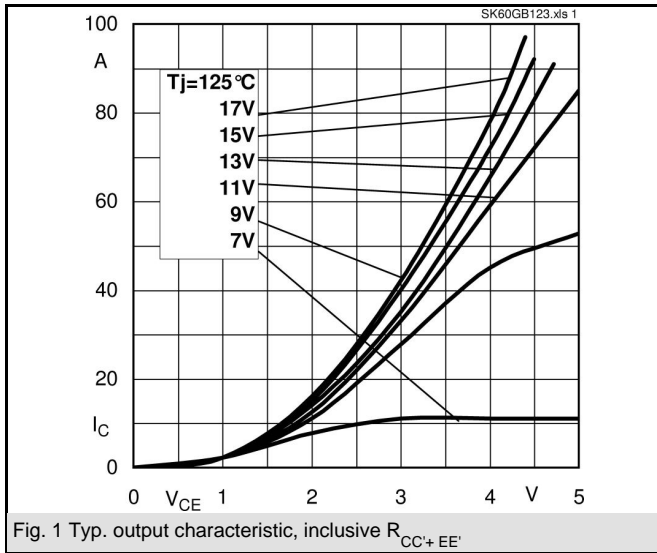
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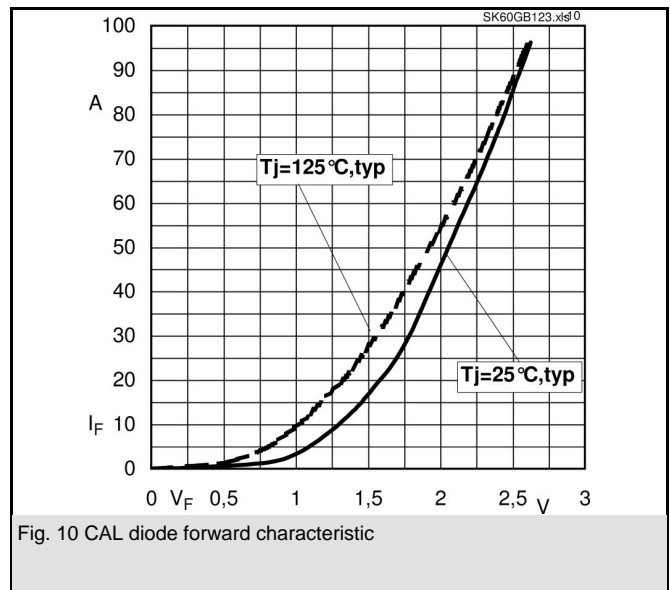
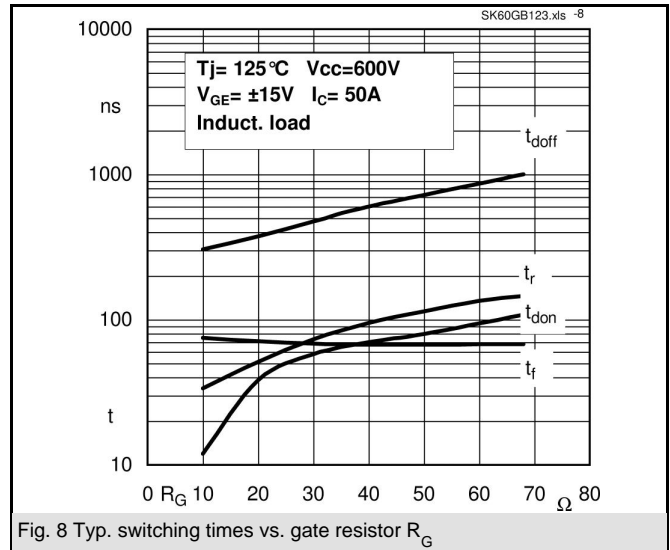
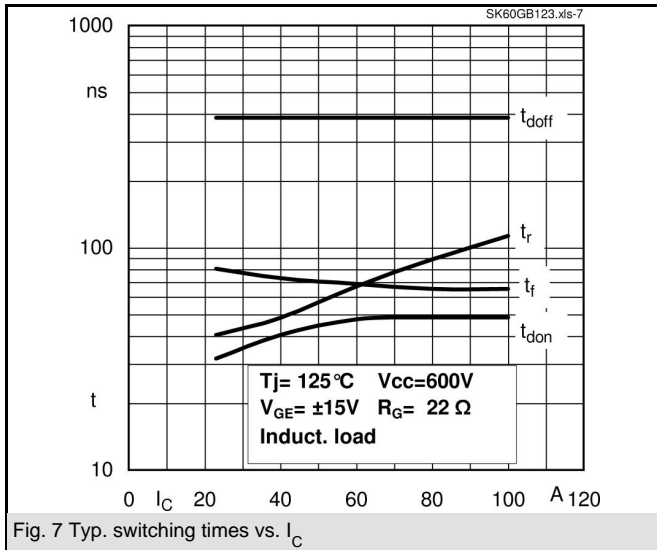
Characteristics

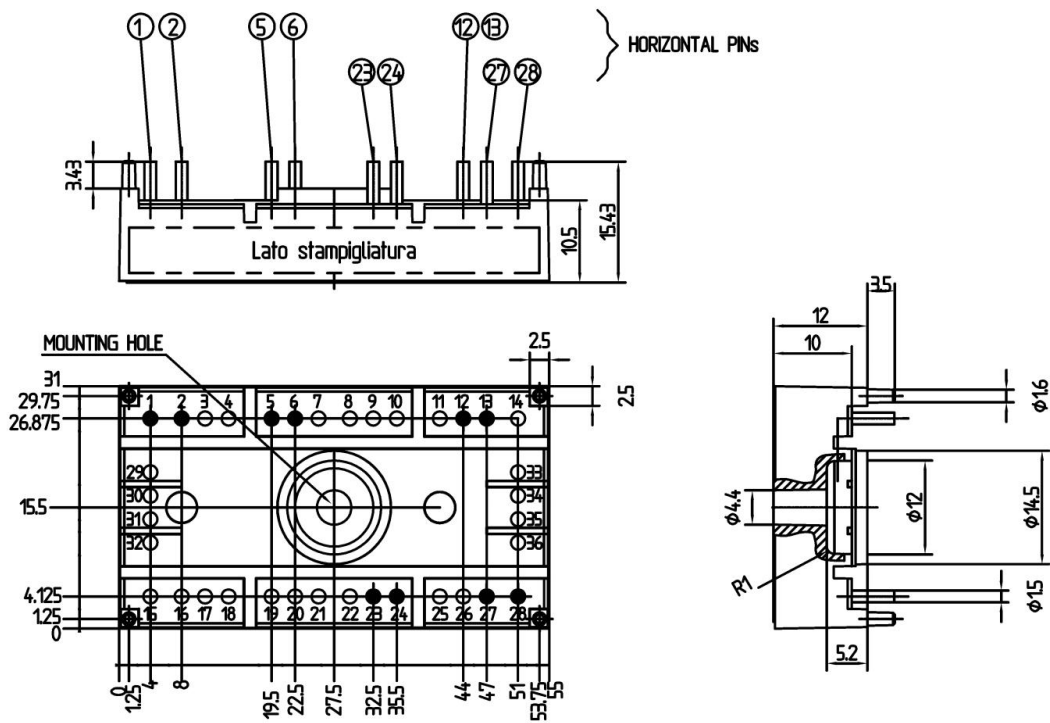
Symbol	Conditions	min.	typ.	max.	Units	
Inverse Diode						
$V_F = V_{EC}$	$I_{Fnom} = 50 \text{ A}; V_{GE} = 0 \text{ V}$		$T_j = 25 \text{ }^\circ\text{C}_{chiplev.}$	2	V	
			$T_j = 125 \text{ }^\circ\text{C}_{chiplev.}$	1,8	V	
V_{F0}			$T_j = 125 \text{ }^\circ\text{C}$	1	1,2	V
r_F			$T_j = 125 \text{ }^\circ\text{C}$	16	22	mΩ
I_{RRM}	$I_F = 50 \text{ A}$		$T_j = 125 \text{ }^\circ\text{C}$	40		A
Q_{rr}	$di/dt = -800 \text{ A}/\mu\text{s}$			8		μC
E_{rr}	$V_{CC} = 600\text{V}$			2		mJ
$R_{th(j-s)D}$	per diode				0,9	K/W
M_s	to heat sink M1	2,25		2,5		Nm
w			30			g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

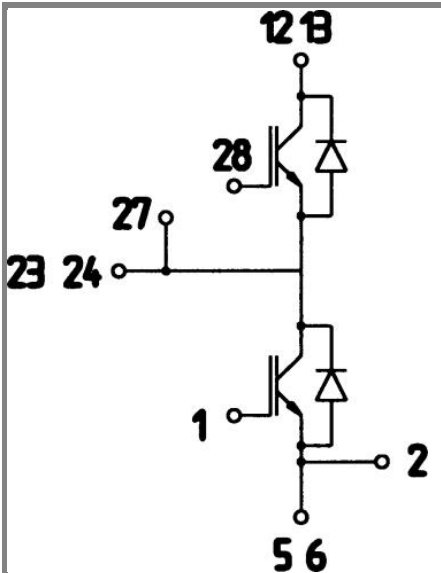
* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.







Case T27 (Suggested hole diameter, in the PCB, for solder pins and plastic mounting pins: 2mm)



Case T27